Lighting Color

• Red

# **LNJ211R82RA**

### Hight Bright Surface Mounting Chip LED

3216 Type

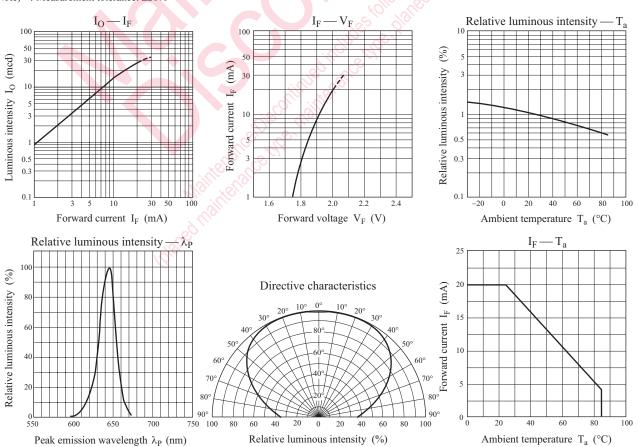
#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P <sub>D</sub>	55	mW	
Forward current	I <sub>F</sub>	20	mA	
Pulse forward current *	I <sub>FP</sub>	60	mA	
Reverse voltage	V <sub>R</sub>	4	V	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

#### Electro-Optical Characteristics $T_a = 25^{\circ}C$

Storage temperature	1 stg	40 10 + 100					
Note) *: The condition of I <sub>FP</sub> is duty 10%, Pulse with	dth 1 msec.						
Electro-Optical Characteristics T <sub>a</sub> =			×	Uni Og	<sup>2</sup> O		
Parameter	Symbol		Conditions	Min	Тур	Max	Unit
Luminous intensity *	Io	$I_F = 10 \text{ mA}$		8	C 15 8	2	mcd
Reverse current	I <sub>R</sub>	$V_R = 4 V$			1000	100	μΑ
Forward voltage	V <sub>F</sub>	$I_F = 10 \text{ mA}$	XII	S COL	1.92	2.50	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_{\rm F} = 10  {\rm mA}$	illos	dillo	645		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		SC.	22		nm





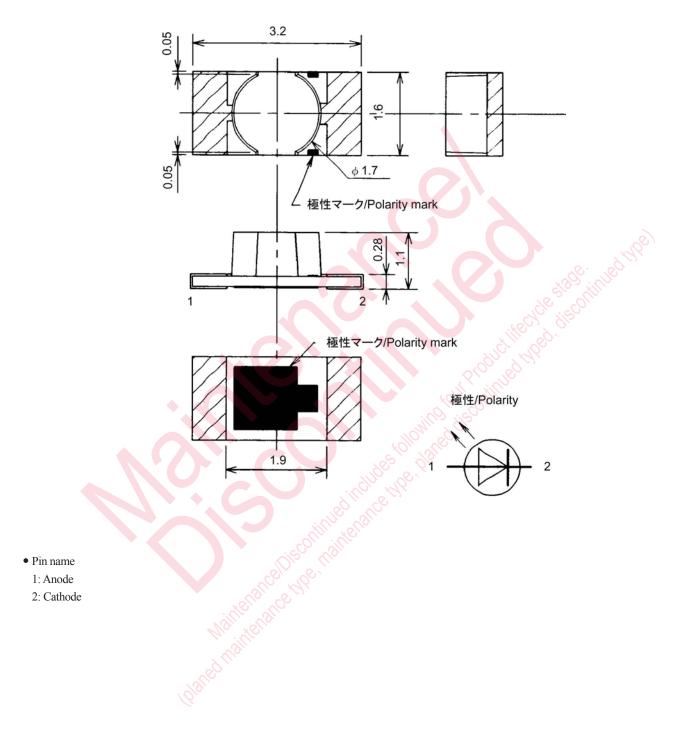
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#### LNJ211R82RA

Package (Unit: mm)

## KLTFTN2K1100



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